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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16757**Generic Copy

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**Issue Date:** 02-Feb-2012

**TITLE:** Qualification of ON Semiconductor's Seremban Site as the die sales assembly site for Seoul Semiconductor Company Ltd (SSC)'s die sales devices

**PROPOSED FIRST SHIP DATE:** 02-May-2012 or earlier with customer approval

**AFFECTED CHANGE CATEGORY(S):** Die Sales assembly site, package

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or Suei Huey Wong<[SueiHuey.Wong@onsemi.com](mailto:SueiHuey.Wong@onsemi.com)>

**SAMPLES:** Contact your local ON Semiconductor Sales Office or Suei Huey Wong<[SueiHuey.Wong@onsemi.com](mailto:SueiHuey.Wong@onsemi.com)>

**ADDITIONAL RELIABILITY DATA:** N/A

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to the implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.

**DESCRIPTION AND PURPOSE:**

ON Semiconductor is pleased to announce that SSC wafer sales devices are now qualified for production (saw, inspection & packaging) at ON Semiconductor's Seremban facility.

Upon expiration or approval of the Final PCN, devices may be supplied from Seremban facility.

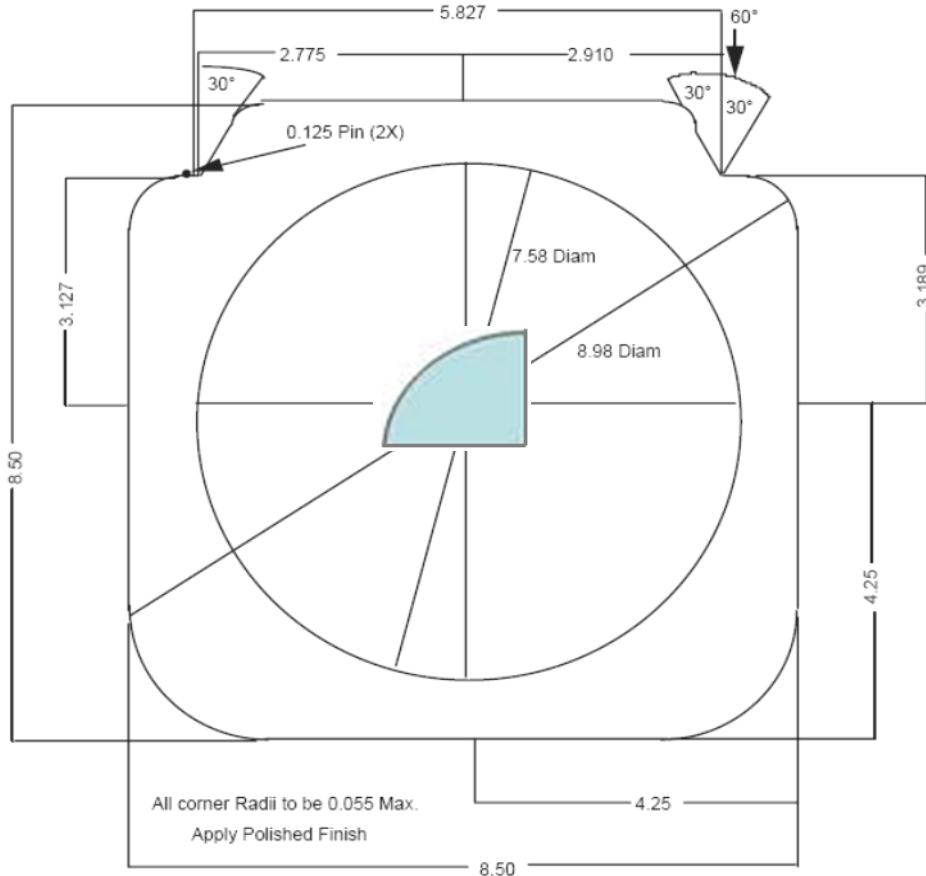
The devices have previously been manufactured at SAWTECH and CEI. Devices are now qualified to run at ON Semiconductor Seremban facility for saw, inspection & packaging. No changes to wafer fab source & device electrical performance as a result of this die sales assembly site qualification.



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**Package Change:**

Packaging method will be changed to quartered sawn wafer mounted on mylar & metal ring, in flexible film frame.



**RELIABILITY DATA SUMMARY:**

There is no significant difference in reliability for the ON Semiconductor Seremban processed wafers.

**ELECTRICAL CHARACTERISTIC SUMMARY:**

There is no significant difference in electrical parametric performance for the CEI processed wafers.

**CHANGED PART IDENTIFICATION:**

Products listed in this PCN with Finished Good date codes representing WW18, 2012 or later will be processed in CEI, unless earlier customer approval is obtained. If early customer approval is obtained, devices with date codes of WW06, 2012 or later will be processed in Seremban.

**List of Affected General Parts:**

CM1771-5006YJQ